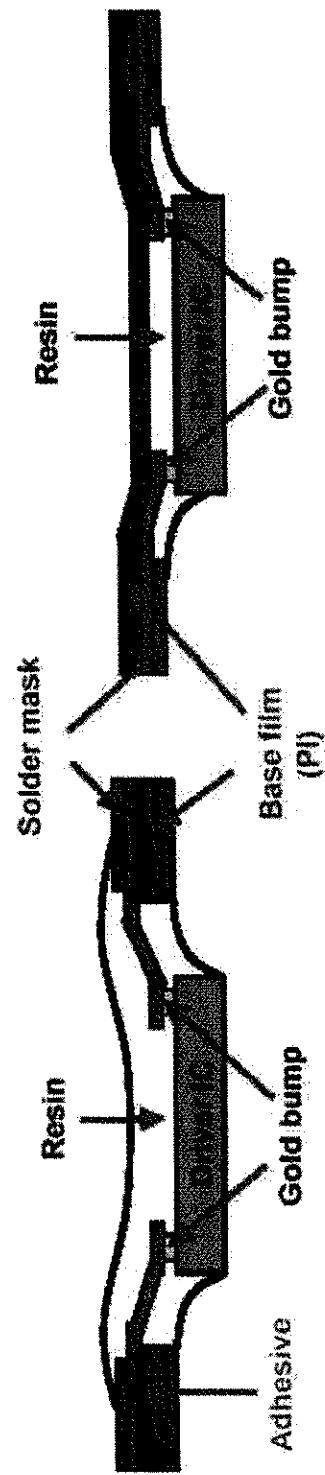
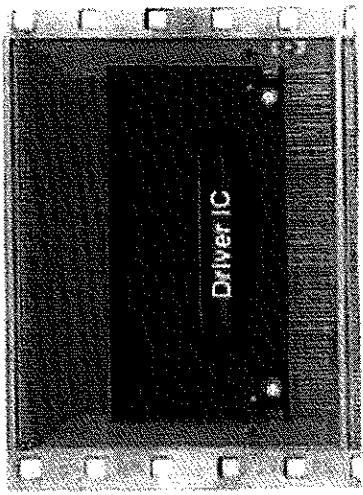
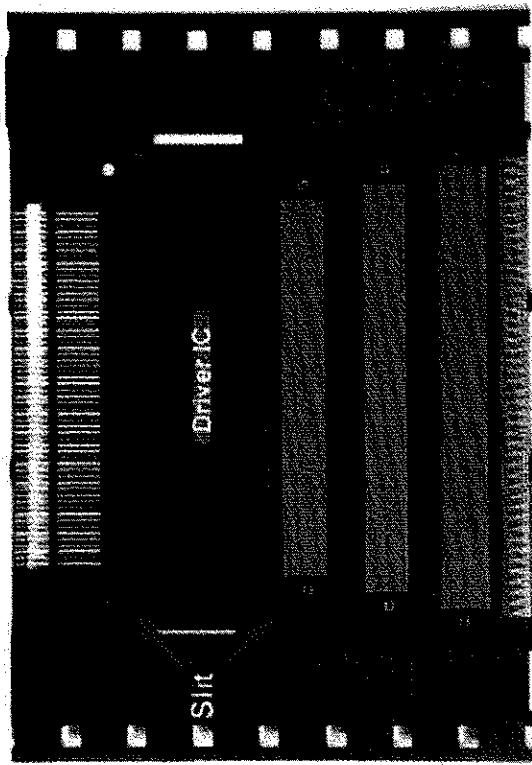


# Exhibit 15

PHILIPS

- TCP&COF package comparison (1/4)



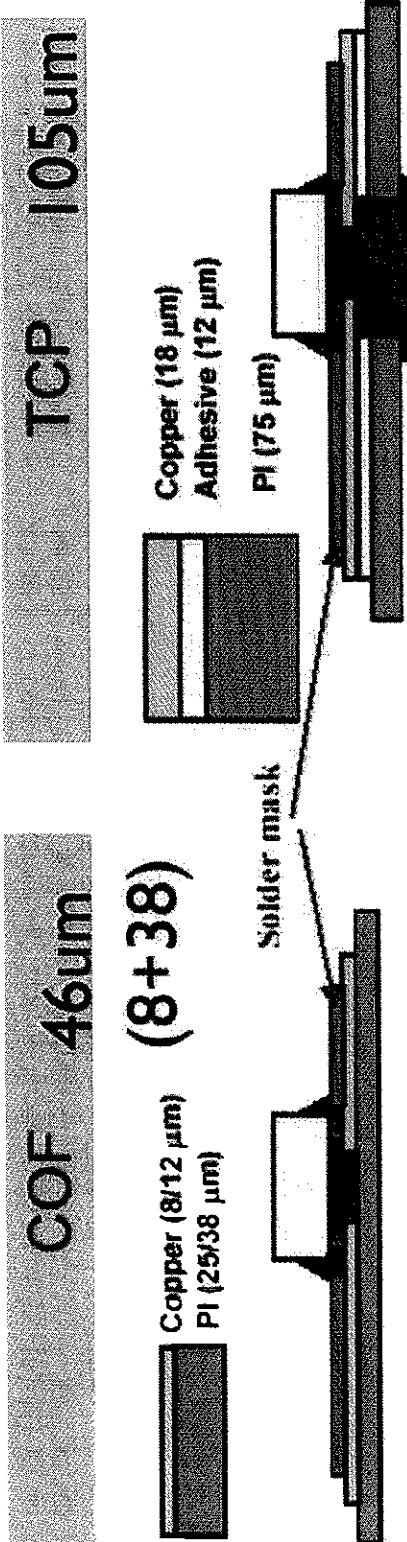
Source: ChipMOS 2001 technology symposium

PSK-TDD, Ni Wu, 2002-05-31

CPT-D 19159

PHILIPS

- TCP&COF package comparison (2/4)



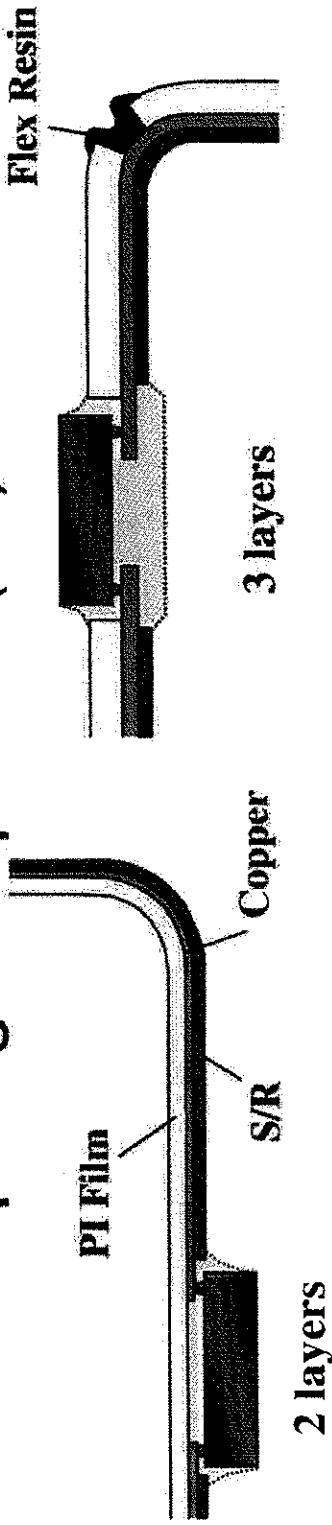
	COF	TCP
Type	Kapton 150EN	Uphilix S
Thickness	25/38 μm	75 μm
Flexibility	Good	Poor
Strength	Average	Good
Bending Slit	No need	Need
ILB Pitch	-30 μm	-45 μm
Device Hole	No need	Need
Copper Foil	Electro-deposited	FQ-VIP
Type	-	18 μm
Thickness	8/12 μm	
Adhesive	-	#7100
Solder Resist	SN-9000 AR-7100	AR-7100 AE-70-M11
Layer	2	3

Source: ChipMOS 2001 technology symposium

PSK-TDD, MJ Wu, 2002-05-31

PHILIPS

- TCP&COF package comparison (3/4)



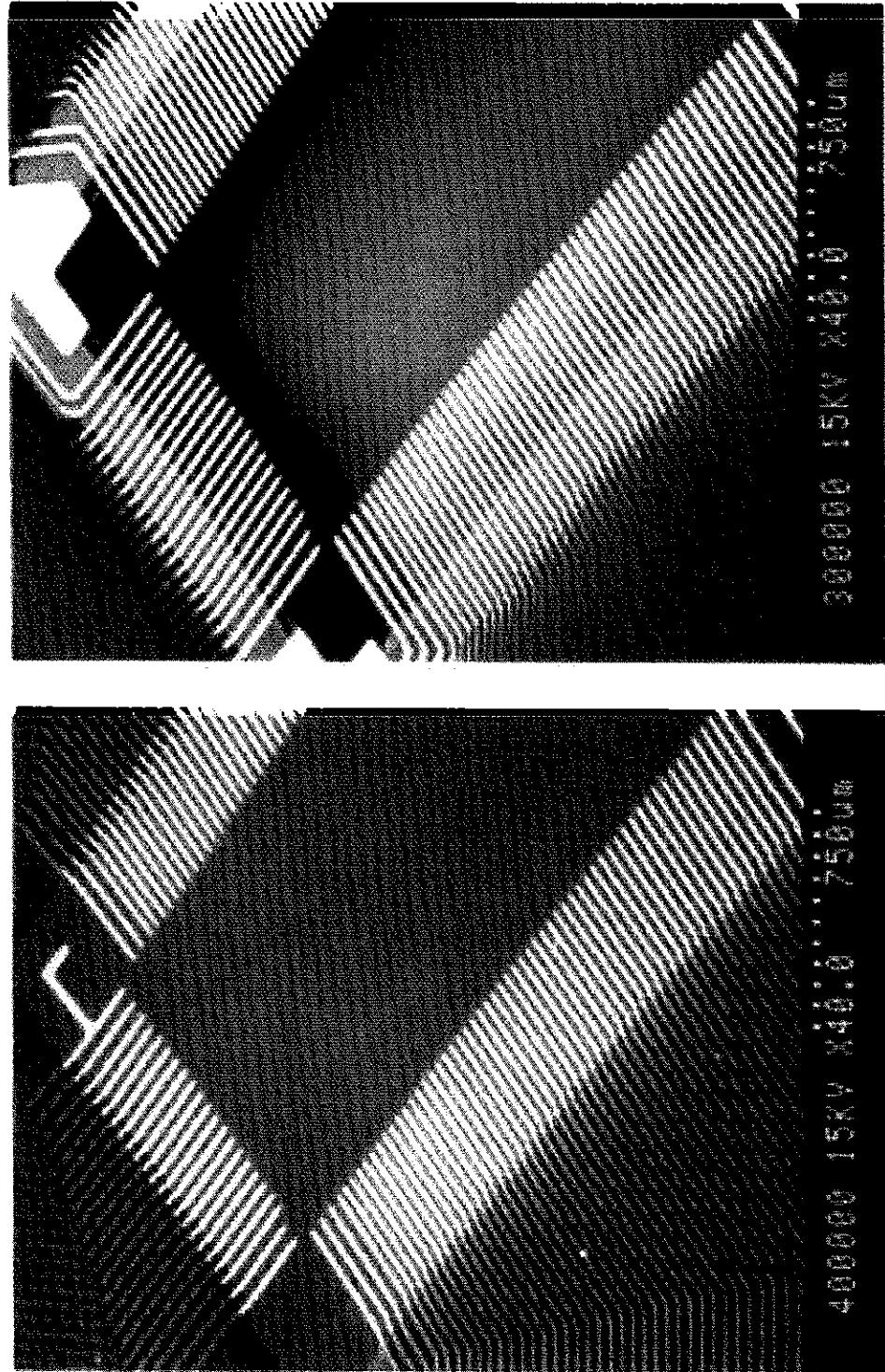
COF	TCP
<ul style="list-style-type: none"> <li>• No Flying Leads</li> <li>• For Finer Pitch Chip</li> <li>• High Flexibility thin film, no flex slit</li> <li>• Can use less sprocket hole</li> <li>• Routing in die area is possible</li> </ul>	<ul style="list-style-type: none"> <li>• Flying Leads</li> <li>• For Min.40um pitch Chip</li> <li>• Flex resin needed</li> </ul>

Source: IST 2002 presentation

PSK-TDD, M. Wenzel, 2002

PHILIPS

- TCP&COF package comparison (4/4)



TCP Photo (x40)  
COF Photo (x40)